

Optical Deformation Chamber using Digital Image Correlation (DIC)

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Motivation

Initial Substrate Design

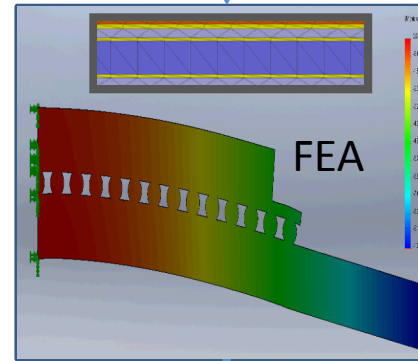
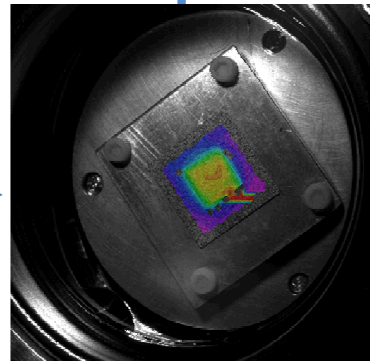
Solder mask, 25 um
Layer 1, 20 um
Prepreg, 40 um
Layer 2, 15 um

BT core 150 um

Layer 3, 15 um
Prepreg, 40 um
Layer 4, 20 um
Solder mask, 25 um

A system was developed to perform experiments which can measure the deformation microsystems components to validate structural models.

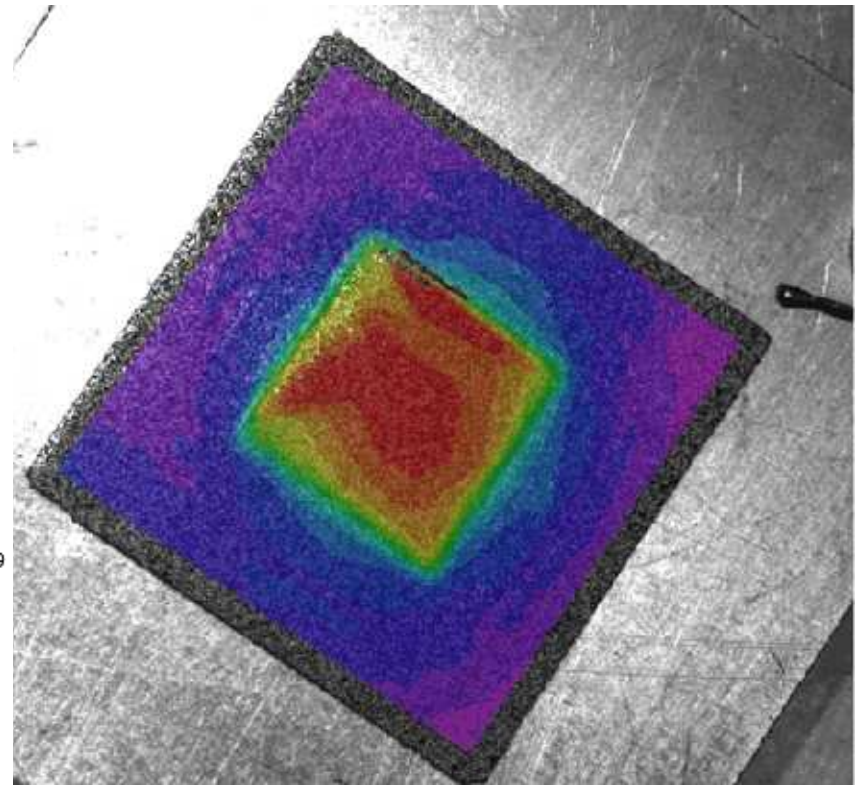
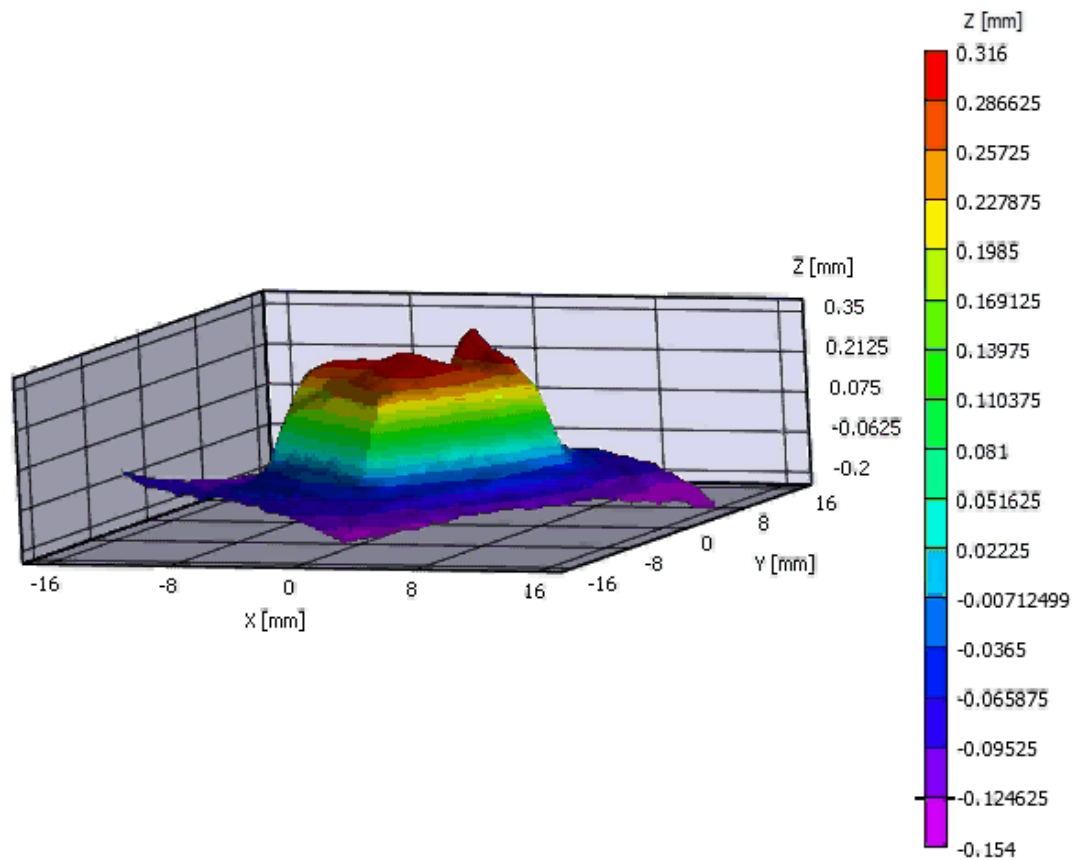
Simulation Based Design



The focus of this work was developing a means of validating structural microsystems models. The data from this experiment can be used to gain trust in the model which can then be used to identify better designs.

New Substrate Design with different laminate structures and thicknesses.

Full 3D and 2D Characterization

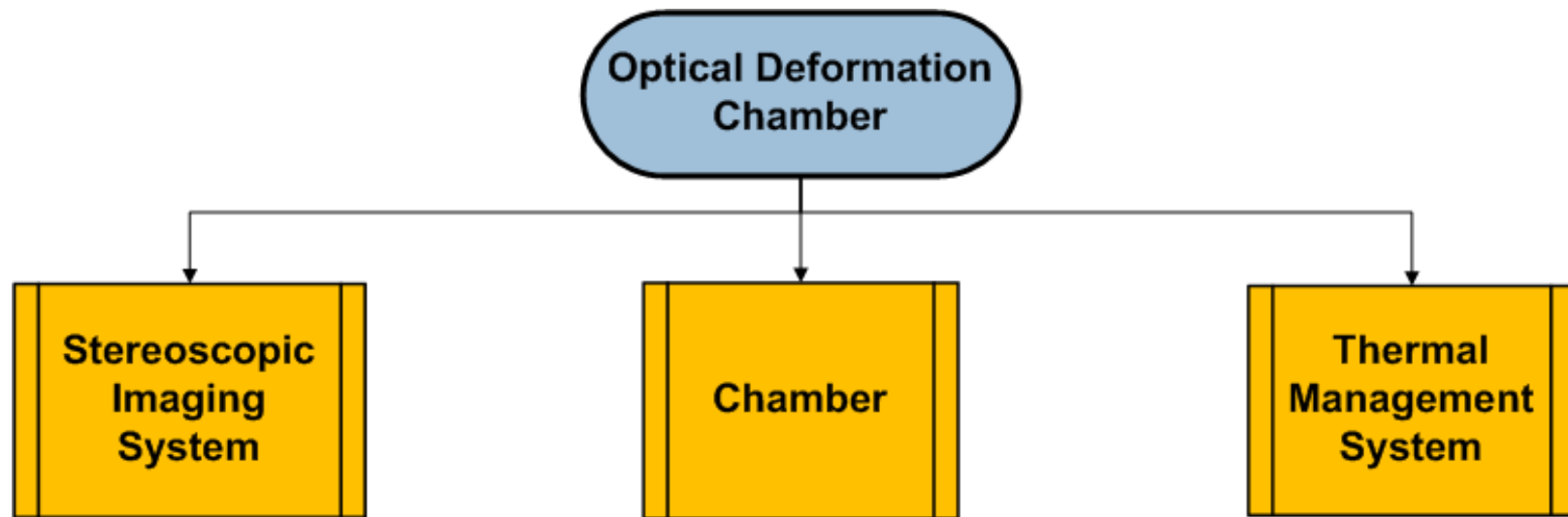




Outline

- **Optical Deformation Chamber Setup**
 - Chamber Design
 - Temperature Cycling System
 - Machine Vision Components
- DIC Method
 - Calibration
 - Image Acquisition
 - Analysis
- Device Testing
 - Thermal Verification
 - Deformation and Strain Analysis
- Concluding Remarks

Optical Deformation Chamber



Controlled imaging environment

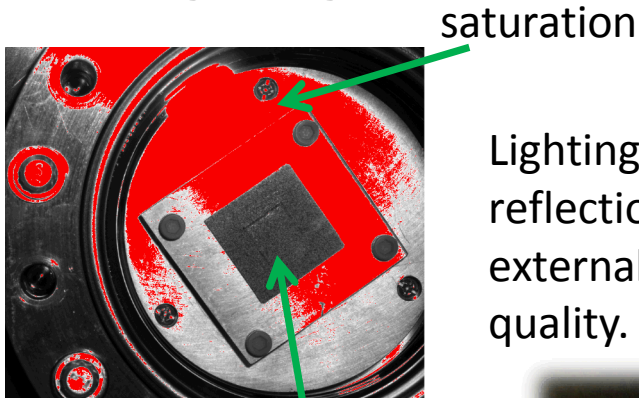
- Eliminate external lighting variation
- Minimize internally reflected light
- Uniform illumination

Flexible and easy device setup

-55°C to 125 °C
Device Temp

Machine Vision System

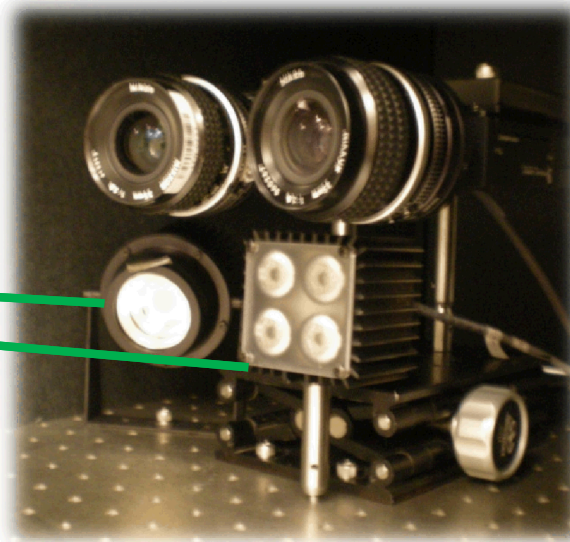
Lighting



Diffuse

Lighting selection, minimizing reflections and eliminating external lighting enhance image quality.

Multiple White
LED light sources

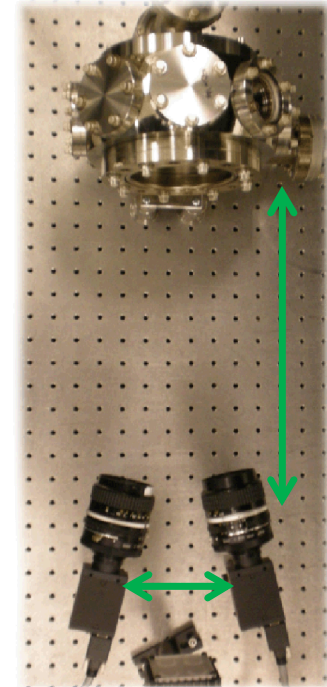


Imaging Software

Vic3D from Correlated Solutions was selected due to its simplicity and ease of use.

6

Stereoscopic Cameras



Extrinsic parameters define camera orientation.

Intrinsic parameters define image point to camera reference frame.

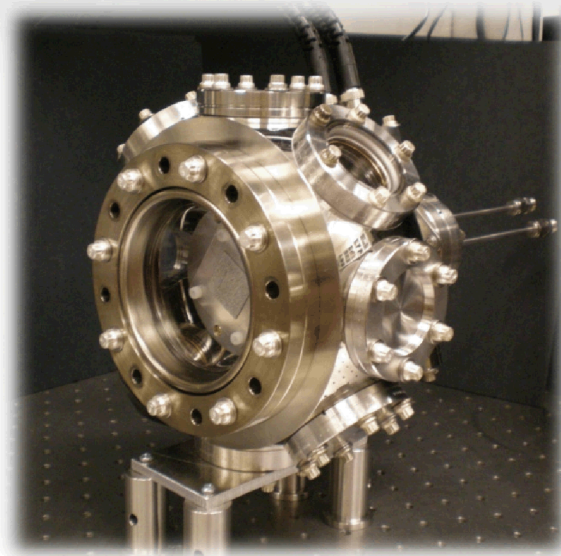
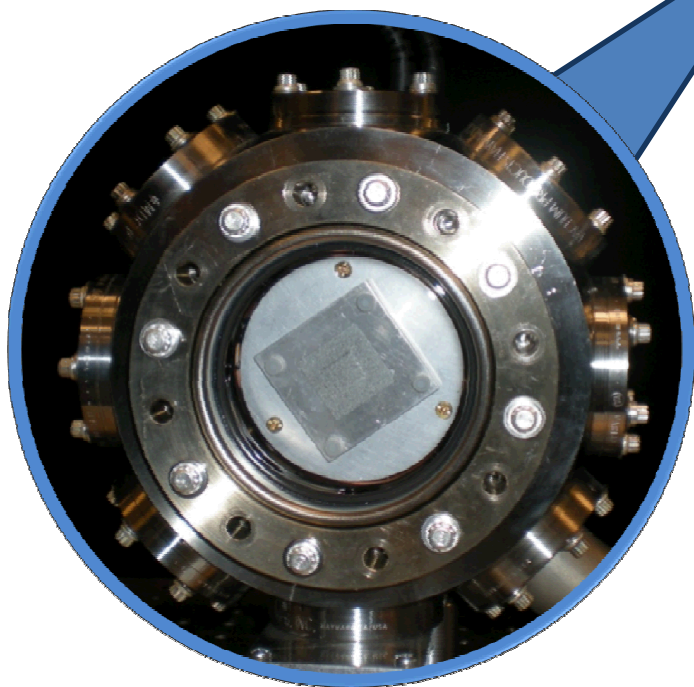
Chamber Design

Components of the chamber

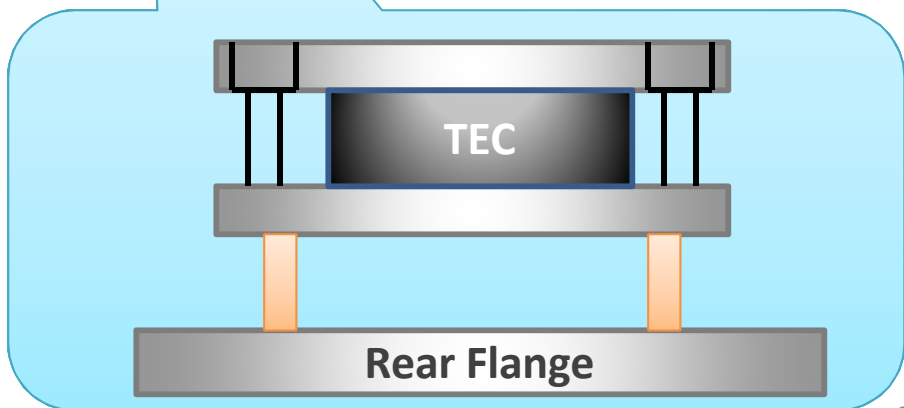
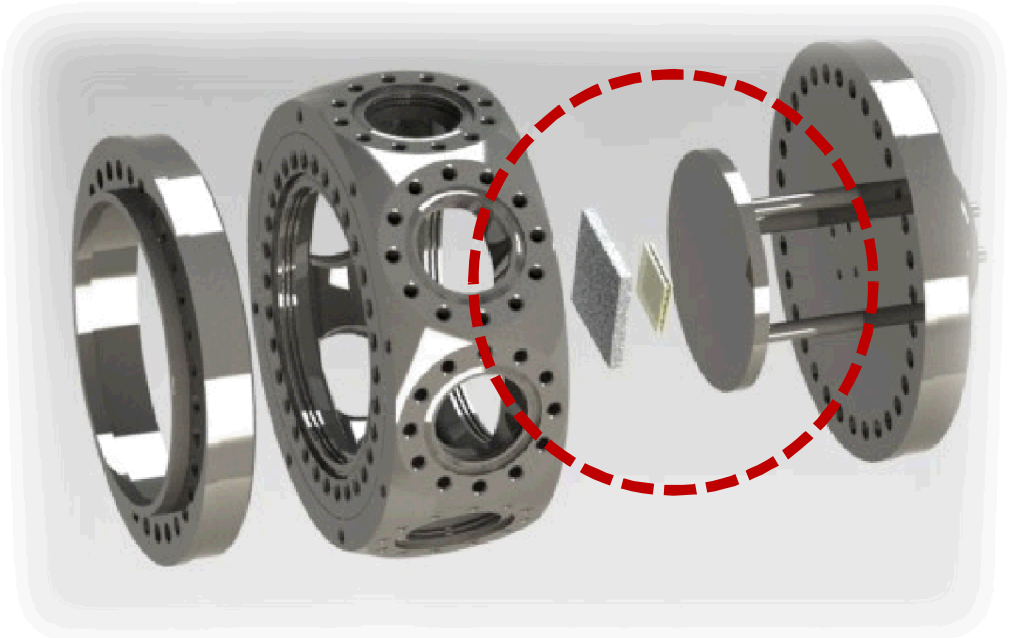
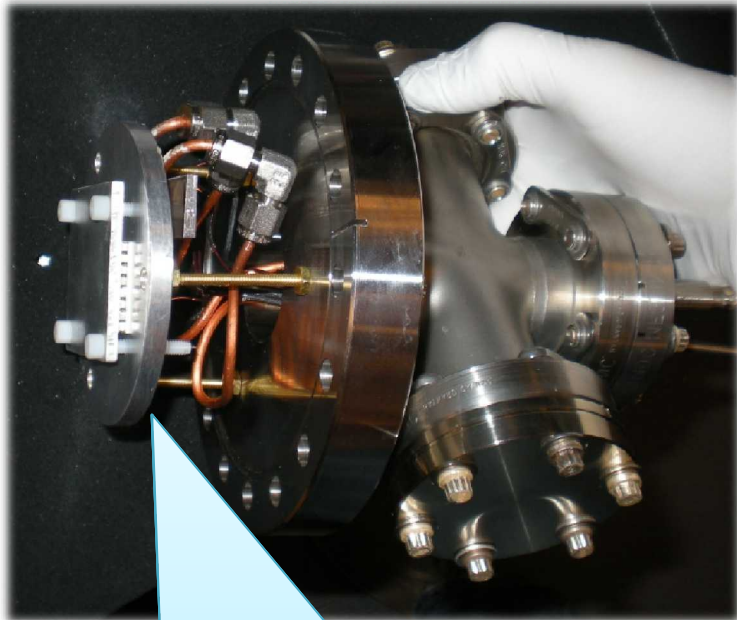
1-Viewing Window

2-Rear flange

3-Mounting plate



Thermal Management Design



The thermoelectric device provides easy integration into the chamber. Flat mounting plate is used for the device under test (DUT).



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DIC Method

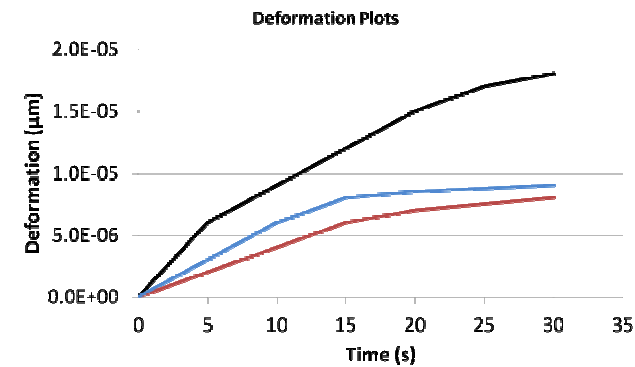
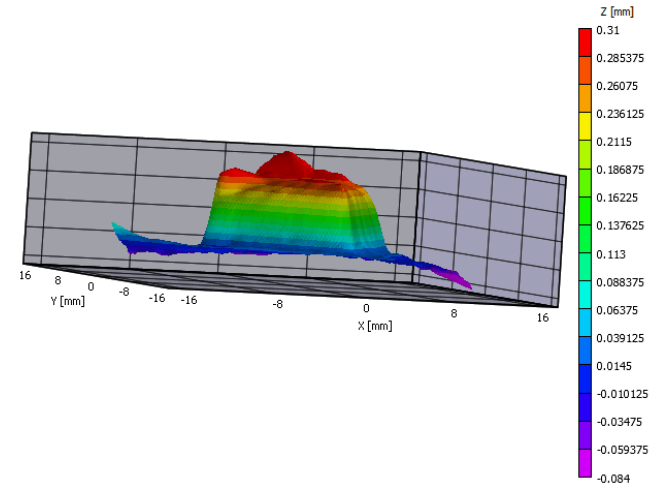
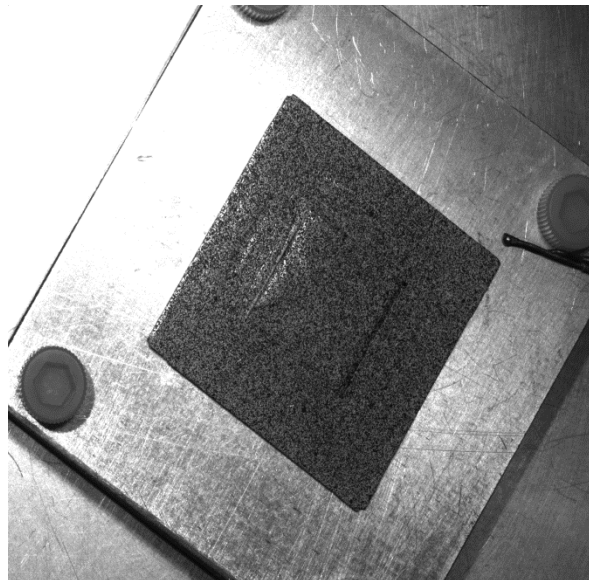
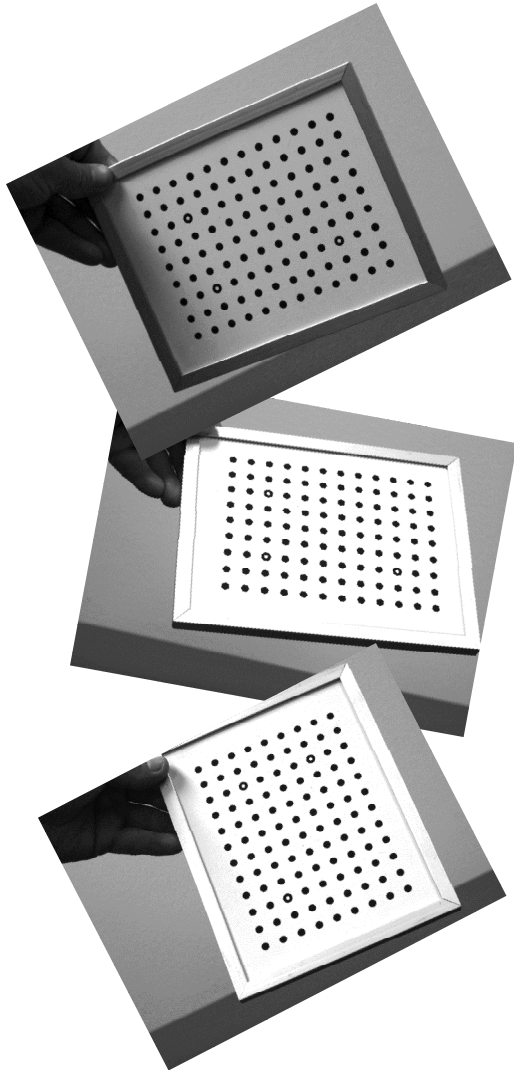
Calibration



Image Acquisition



Analysis



Calibration



Translation of target grid determines intrinsic properties of imaging setup.

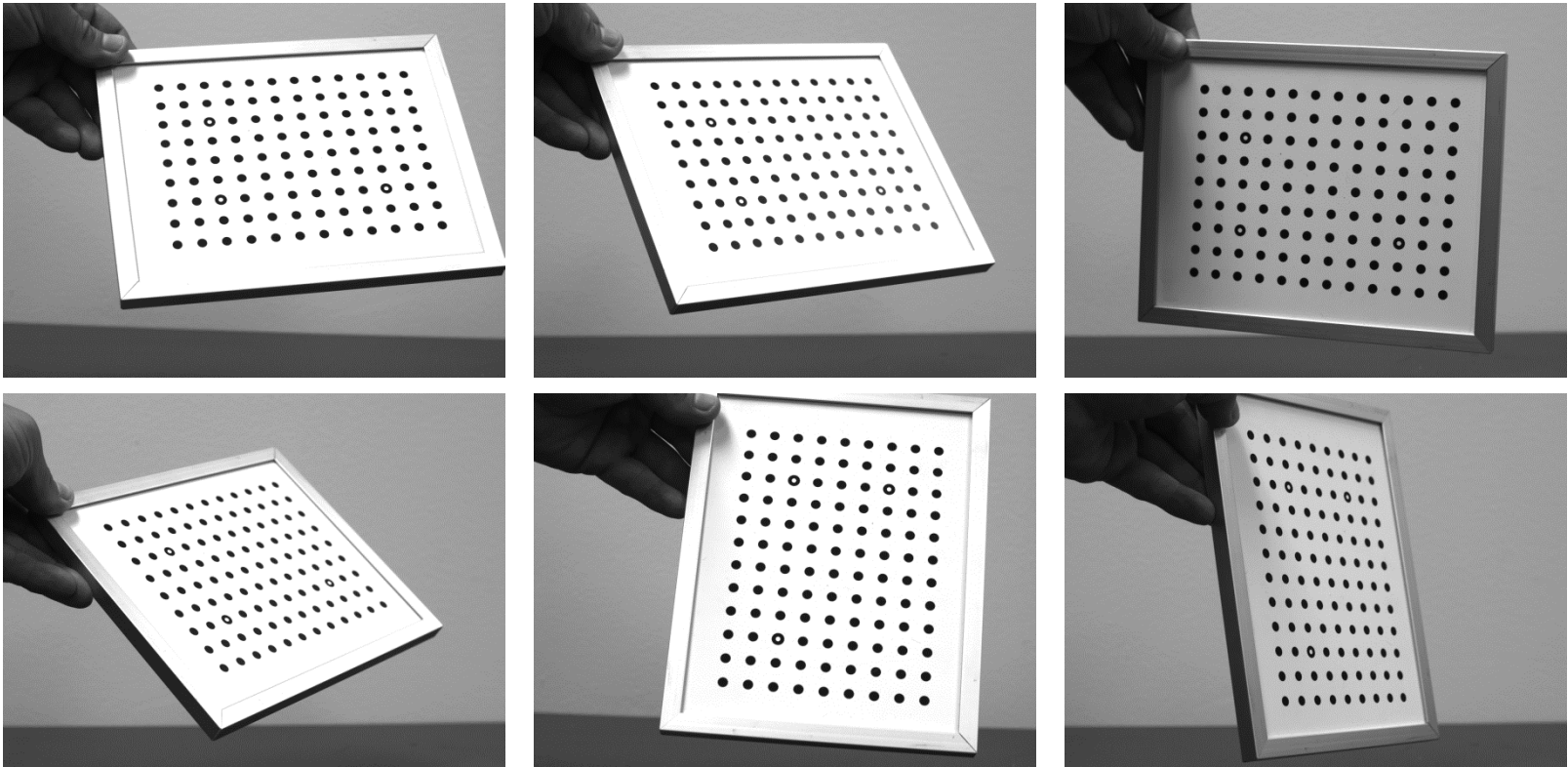
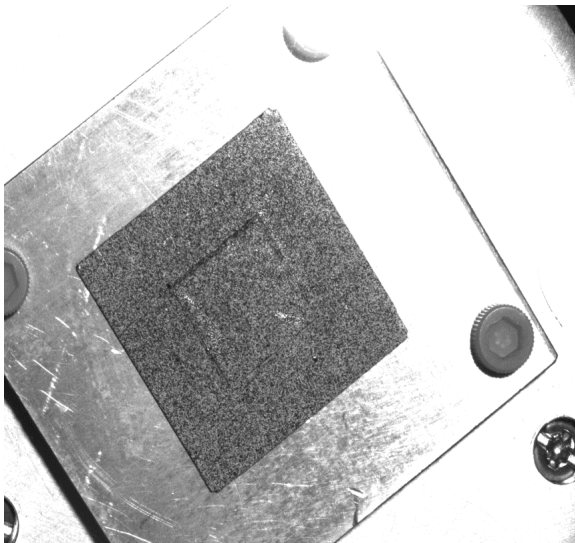
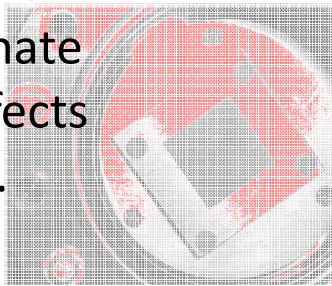


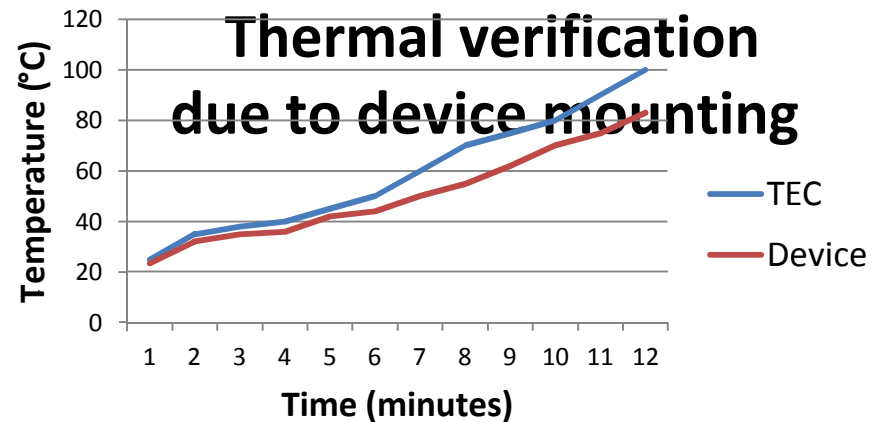
Image Acquisition



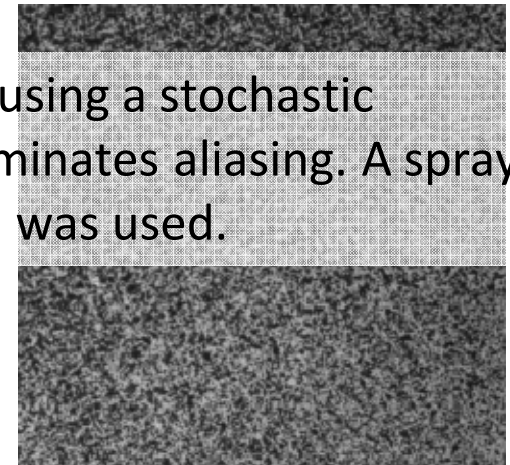
Final lighting adjustment can sometimes eliminate unwanted lighting effects and aid in calibration.



Device Temperature Profile



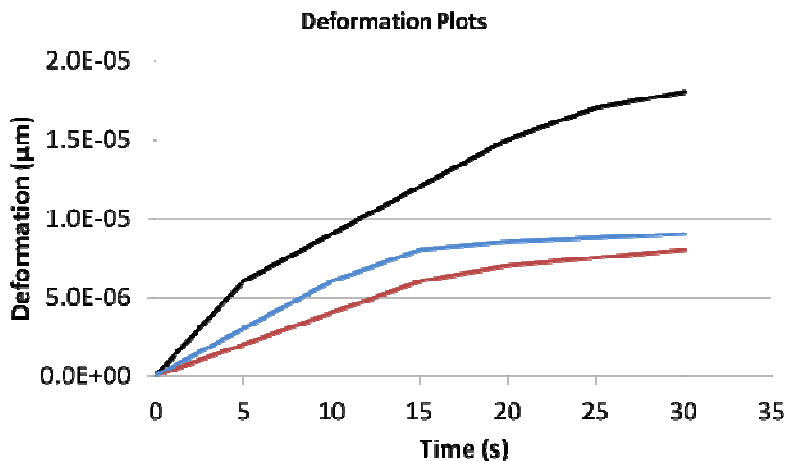
Speckling using a stochastic pattern eliminates aliasing. A spray application was used.



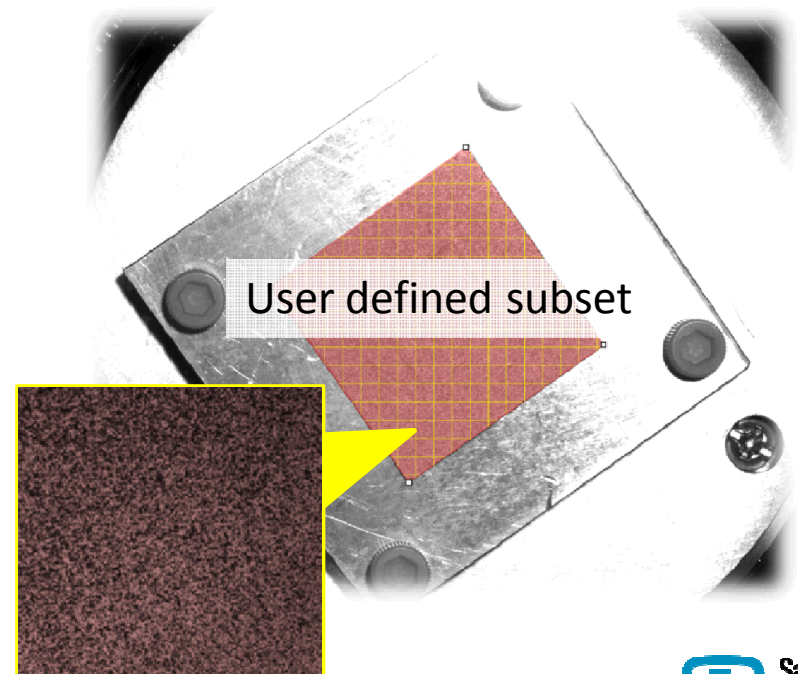
Post Process /Analysis



- Deformation measurement on an object surface.
- Monitors grey values “speckle pattern” for user defined subset.



Update plot ^

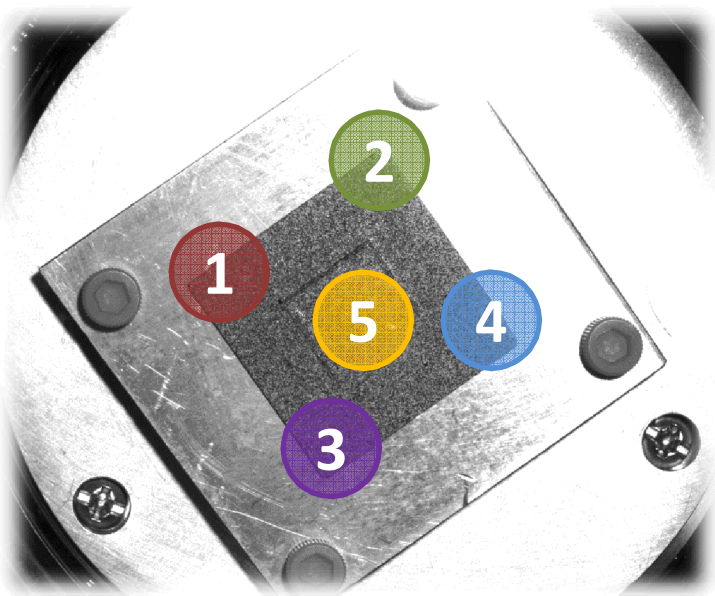




Outline

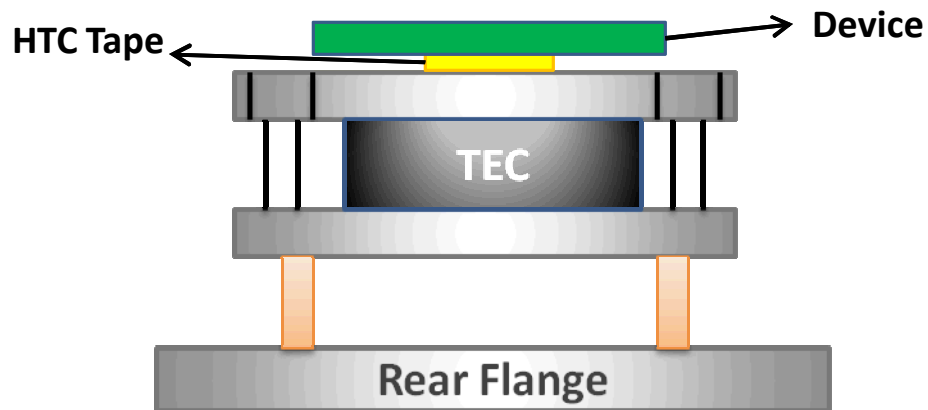
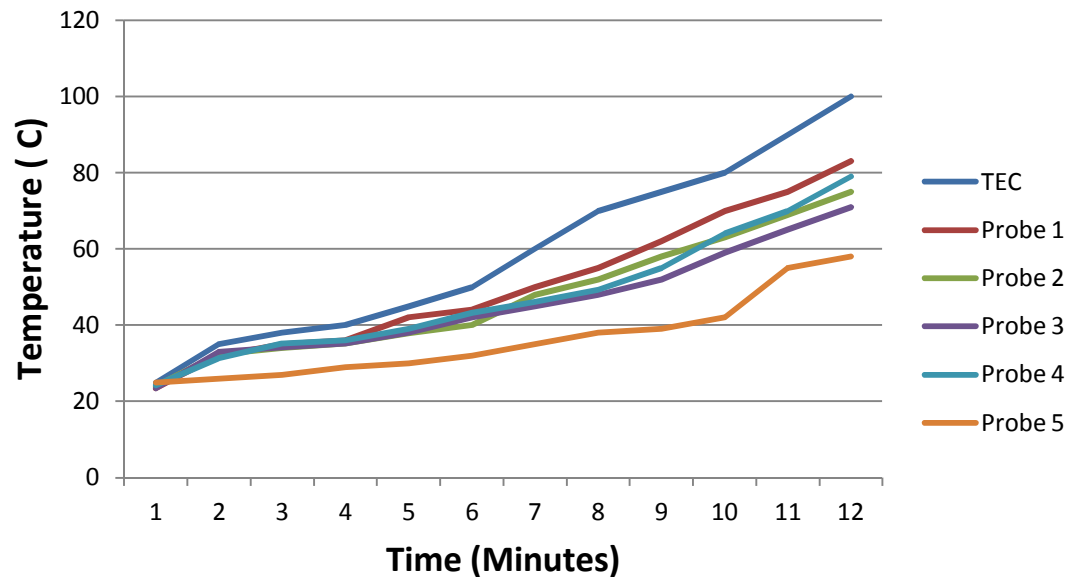
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Thermal Verification



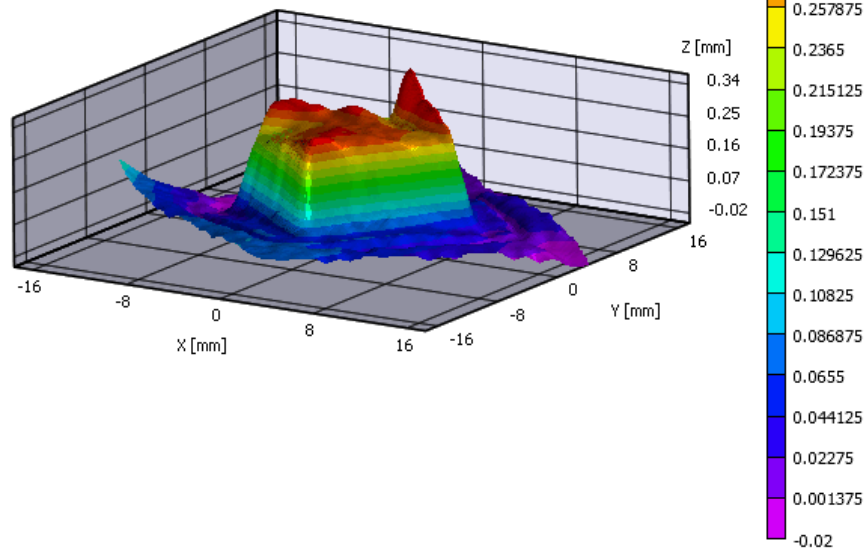
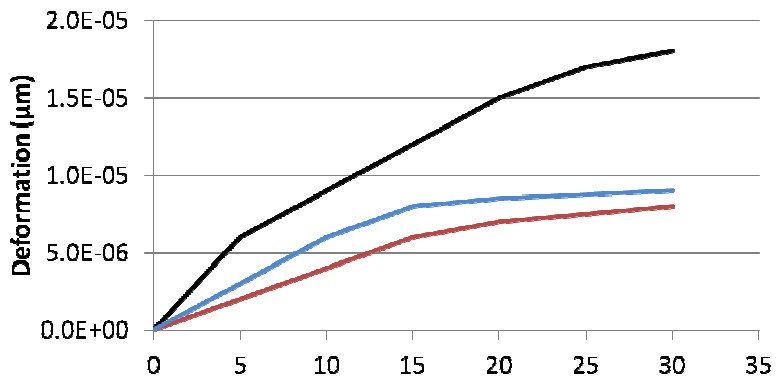
Thermocouples readings at points of interest (1-5).

Device Temperature Verification

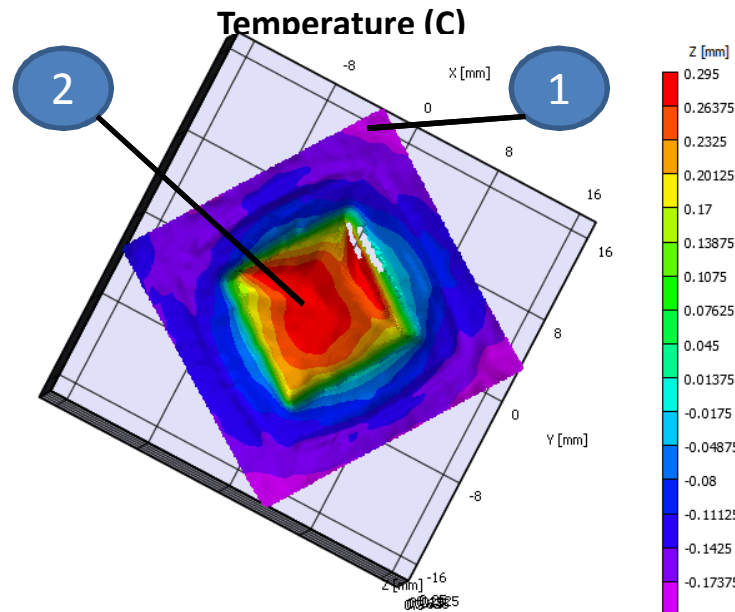
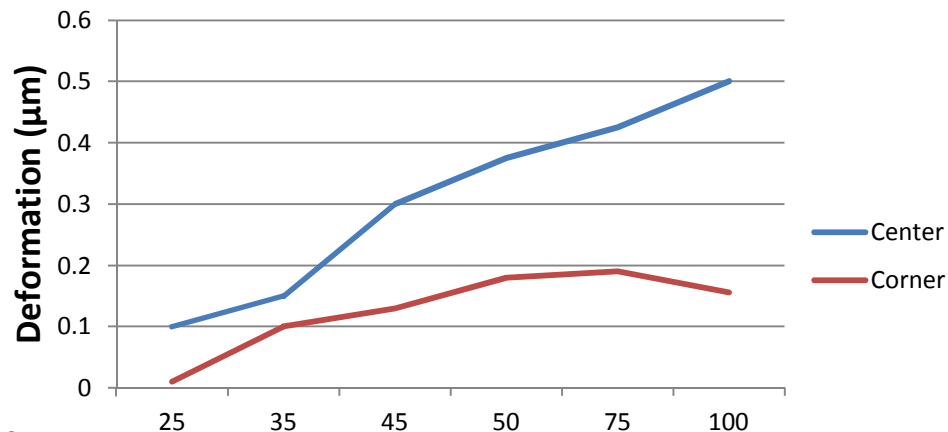


Deformation Analysis

Deformation Plots



Device Deformation

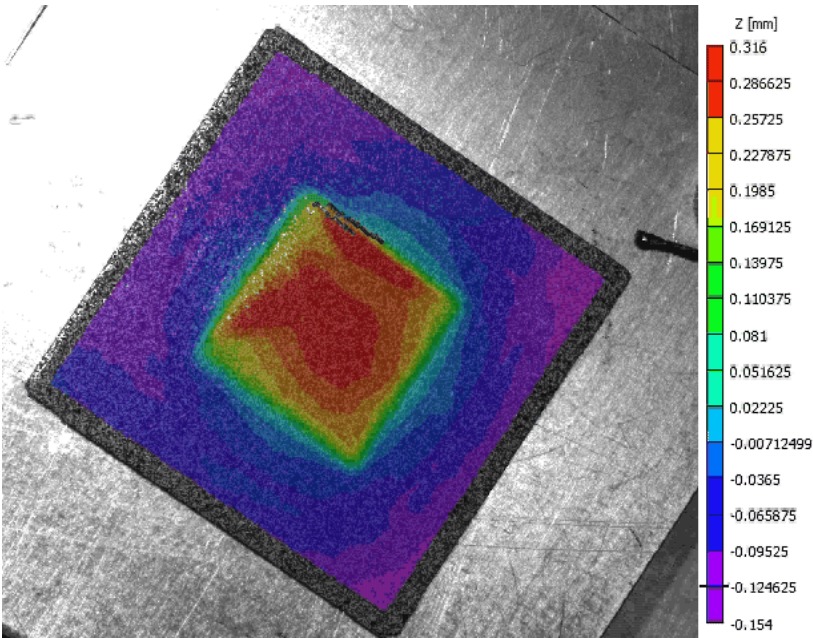
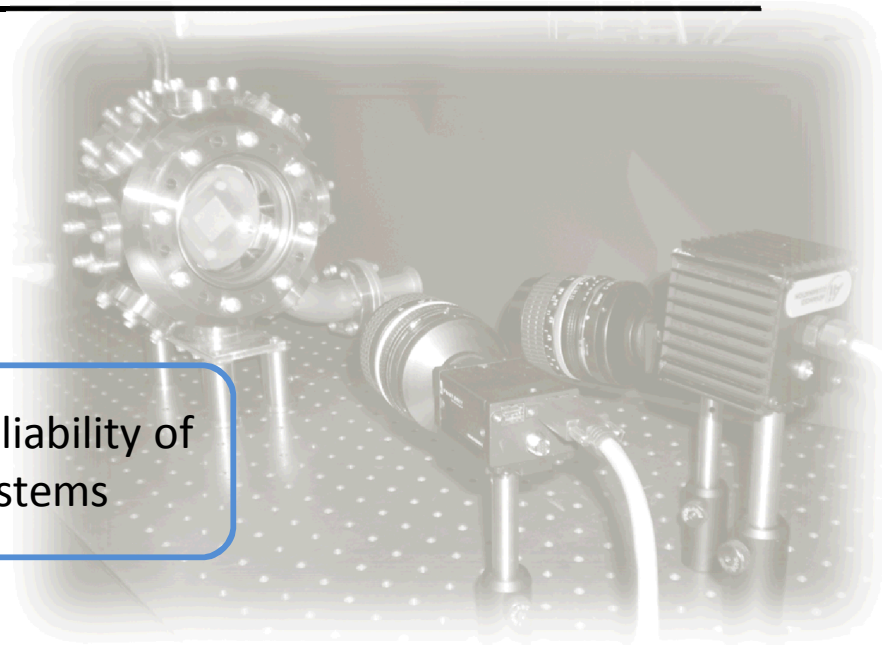


Concluding Remarks

Thermal Induced
Deformation
Characterization

Structural Model
Validation

Enhanced reliability of
microsystems



Acknowledgements

Todd Barrick, Phil Reu, Emil Kadlec